

1 [0064]

**ABSTRACT OF THE DISCLOSURE**

2 [0065] Disclosed herein is a method of roughening a ceramic surface by forming  
3 mechanical interlocks in the ceramic surface by a chemical etching process, a thermal etching  
4 process, or a laser micromachining process. Also disclosed herein are components for use  
5 in semiconductor processing chambers (in particular, a deposition ring for use in a PVD  
6 chamber) which have at least one ceramic surface having mechanical interlocks formed  
7 therein by chemical etching, thermal etching, or laser micromachining. Ceramic surfaces  
8 which have been roughened according to the chemical etching, thermal etching, or laser  
9 micromachining process of the invention are less brittle and damaged than ceramic surfaces  
10 which are roughened using conventional grit blasting techniques. The method of the  
11 invention results in a roughened ceramic surface which provides good adherence to an  
12 overlying sacrificial layer (such as aluminum).